

**■ Features**

- Molding Inductor.
- High reliability.
- High current, low DCR, high efficiency.
- Very low acoustic noise and very low leakage flux noise.
- Operating temperature: -55°C ~ +125°C (Including self-temperature rise) .

**■ Applications**

- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.
- DC/DC converter.

**■ Product Identification**



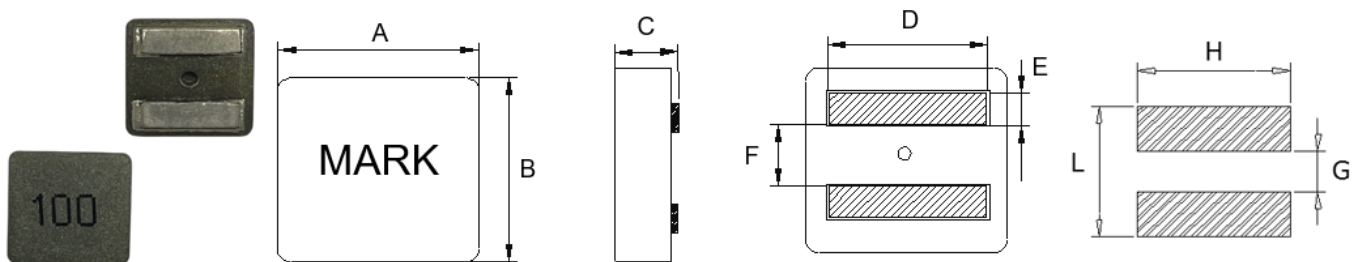
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance : N=±30%,M=±20%

**■ Shapes and Dimensions (Unit: mm)**



TYPE	A	B	C	D	E	F	G Ref.	H Ref.	L Ref.
YSPIT0720A	7.8±0.3	7.6±0.2	1.85±0.2	6.4±0.5	1.75±0.3	3.15±0.3	2.8	7.2	7.4

## ■ YSPIT0720A Series

Part Number	Inductance (uH) @100KHz/0.1V	DCR Max. (mΩ)	Saturation Current (A)		Heat Rating Current Typ.(A)	
			Max.	Typ.	20°C rise	40°C rise
YSPIT0720A-R27M	0.27±20%	3.5	32.0	35.0	16.0	21.0
YSPIT0720A-R31M	0.31±20%	4.8	31.0	34.0	14.0	20.0
YSPIT0720A-R33M	0.33±20%	4.8	31.0	34.0	13.0	19.0
YSPIT0720A-R47M	0.47±20%	6.2	25.0	28.0	12.0	17.0
YSPIT0720A-R68M	0.68±20%	9.2	23.0	25.0	10.0	13.0
YSPIT0720A-1R0M	1.0±20%	10.8	20.0	23.0	8.0	11.0

- ※ The saturation current value is the DC current value having inductance decrease down to 30%.(at 25°C)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40°C. (at 25°C)
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

## ■ Mechanical Reliability

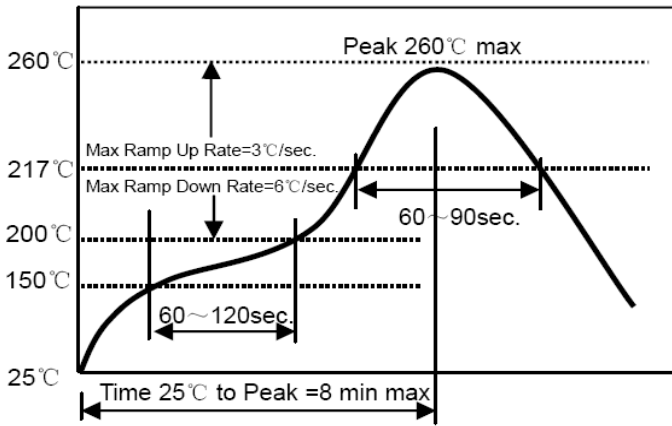
Item	Specification and Requirement	Test Method
Solderability	1. No case deformation or change in visual 2. New solder coverage More than 95%	1.Preheat : 155°C±5°C , 60S±2S 2.Tin: lead-free. 3.Temperature:240°C±5°C , flux 3.0S±0.5S.
Mechanical shock	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Acceleration : 100G 2. Pulse time: : 6ms 3. 3 times in each positive and negative direction of 3 mutual perpendicular directions
Mechanical vibration	1. No case deformation or change in visual 2. $\Delta L/L_0 \leq \pm 10\%$	1. Reflow: 2times 2. Frequency: 10HZ ~ 50HZ ~ 10HZ, 20 Min/Cycles 3. Amplitude: 1.52 mm±10% 4. Directions: X,Y,Z 5. Time: 12 cycle / direction

## ■ Endurance Reliability

Item	Specification and Requirement	Test Method
Thermal Shock	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. First -55°C° for 30 minutes, last 125°C° for 30 minutes as 1 cycle. Go through 1000 cycles. 2. Max transfer time is 3 minutes. 3. Measured at room temperature after placing for 24±2 hours
Biased Humidity	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1.Reflow 2 times, 2.85°C°±3C°,85%±3%RH,1000 hours 3.Measured at room temperature after placing for 24±2 hours
Low temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature : -55 $\pm$ 2C° 2. Time : 1000 hours 3. Measured at room temperature after placing for 24±2 hours
High temperature storage	Inductance change: Within $\pm 10\%$ Without distinct damage in visual	1. Temperature : +125 $\pm$ 2C° 2. Time : 1000 hours 3. Measured at room temperature after placing for 24±2 hours

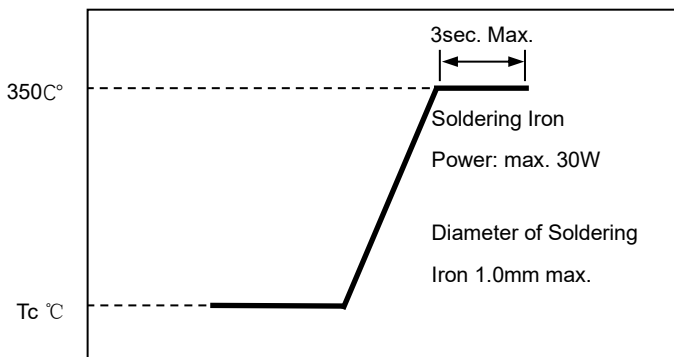
**Recommended Soldering Technologies**

**Re-flowing Profile**



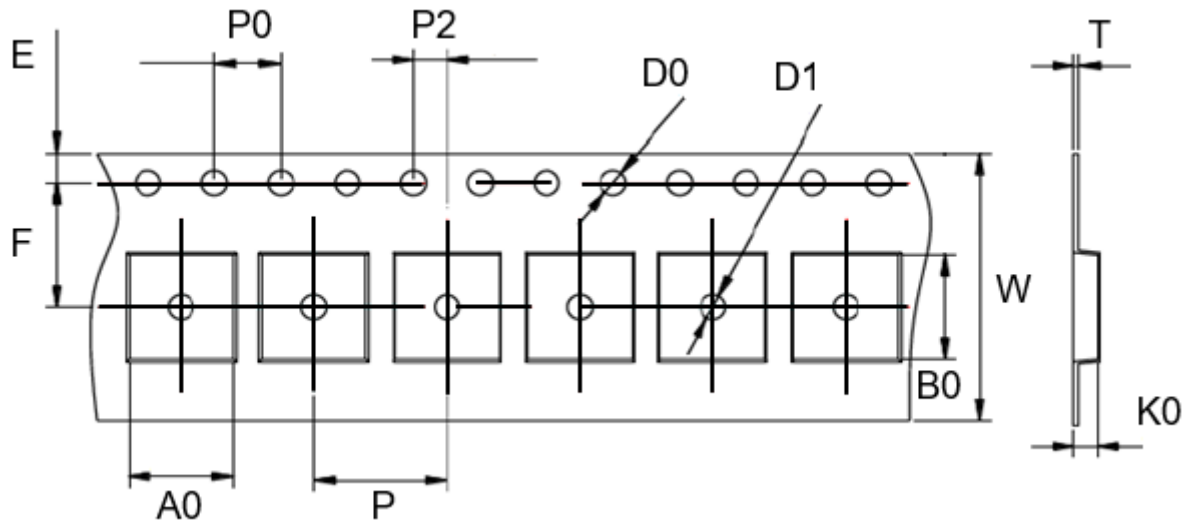
Preheat condition: 150 ~200°C/60~120sec.  
 Allowed time above 217°C: 60~90sec.  
 Peak temp: 260°C  
 Max time at Peak temp: 10 sec.  
 Solder paste: Sn/3.0Ag/0.5Cu  
 Allowed Reflow time: 2x max

**Iron Soldering Profile**



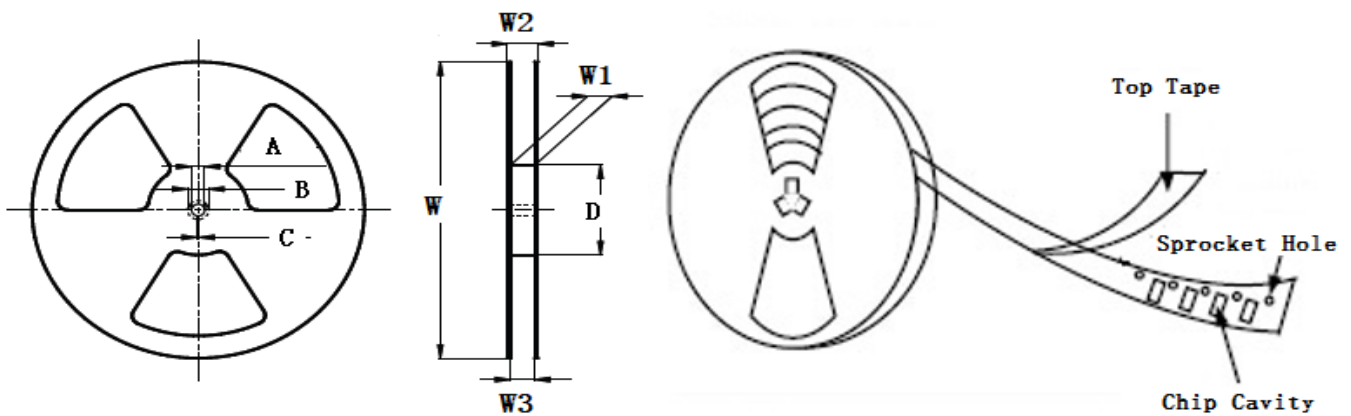
Iron soldering power: Max. 30W  
 Pre-heating: 150°C/60sec.  
 Soldering Tip temperature: 350°C Max.  
 Soldering time: 3sec. Max.  
 Solder paste: Sn/3.0Ag/0.5Cu  
 Max.1 times for iron soldering

**■ Taping Dimensions(Unit:mm)**



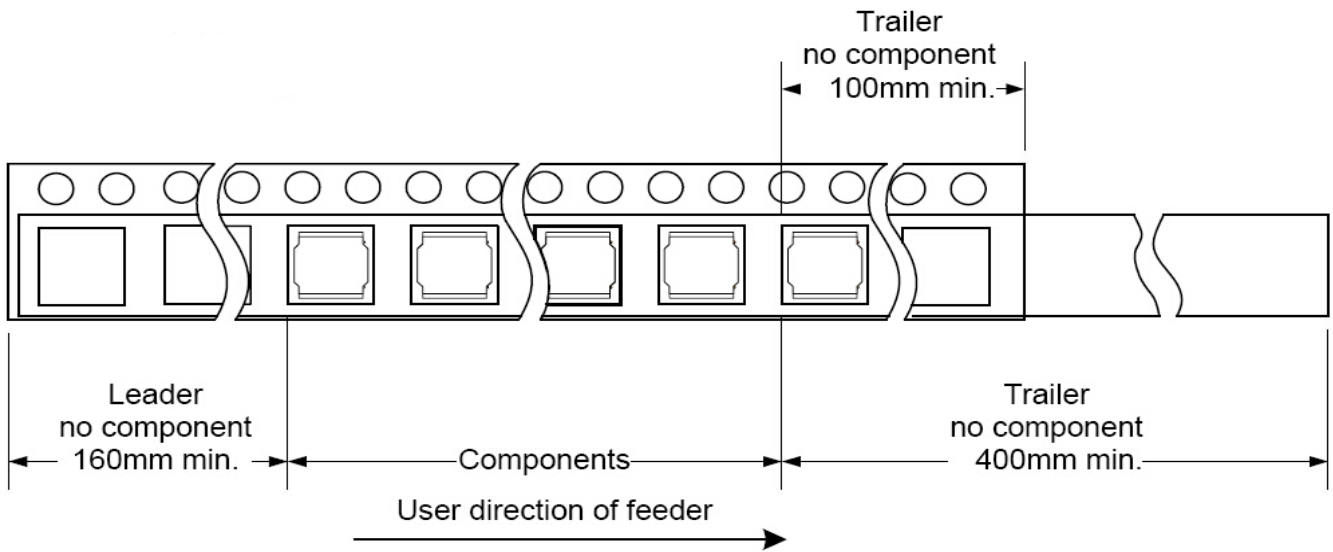
TYPE	W	P	P0	P2	D0	D1	T	A0	B0	K0	E	F	MPQ
YSPIT0720A	16 ±0.3	12 ±0.1	4 ±0.1	2 ±0.1	1.5 ±0.1	1.5 ±0.1	0.35 ±0.05	8.2 ±0.1	8.0 ±0.1	2.3 ±0.1	1.75 ±0.1	7.5 ±0.1	2000

**■ Reel Dimensions(Unit:mm)**

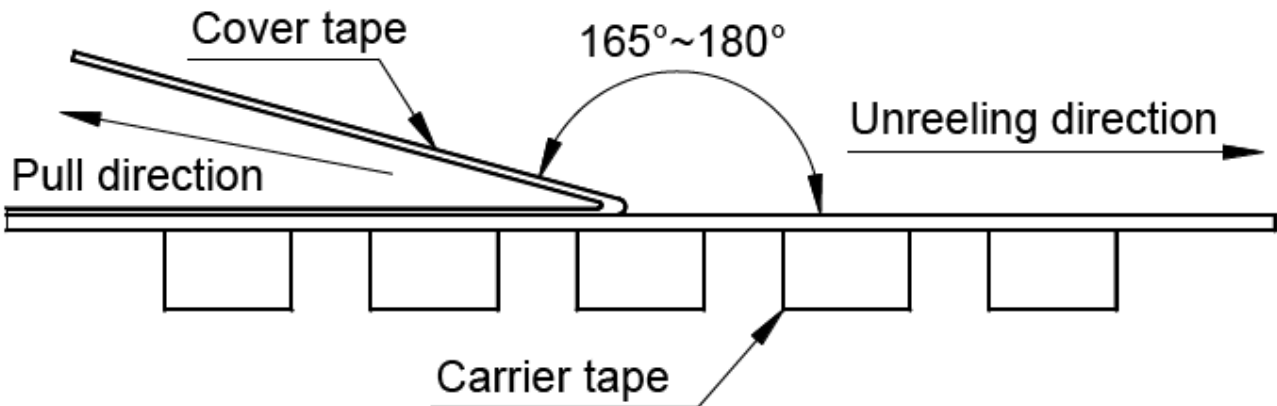


TYPE	W	W1	W2	W3	A	B	C	D
YSPIT0720A	330±2.0	16.4±2.0	22.4MAX	15.9 Min	13.0±0.5	21.0±0.8	2.0±0.5	97±0.5

**Direction of rolling**



**Cover tape peel off condition**



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.